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Details	
Product Status	Obsolete
Number of LABs/CLBs	21248
Number of Logic Elements/Cells	531200
Total RAM Bits	28033024
Number of I/O	654
Number of Gates	-
Voltage - Supply	0.92V ~ 0.98V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-HBGA (42.5x42.5)
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Chapter Revision Dates

The chapters in this document, Stratix IV Device Handbook, were revised on the following dates. Where chapters or groups of chapters are available separately, part numbers are listed.

Chapter 1. DC and Switching Characteristics for Stratix IV Devices

Revised: September 2014 Part Number: SIV54001-5.9

Chapter 2. Addendum to the Stratix IV Device Handbook

Revised: February 2011 Part Number: SIV54002-1.5



Conditions other than those listed in Table 1–1, Table 1–2, and Table 1–3 may cause permanent damage to the device. Addition ally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 1–1. Absolute Maximum Ratings for Stratix IV Devices

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Core voltage and periphery circuitry power supply	-0.	5 1.3	35
V _{CCPT}	Power supply for programmable power technology	-0.	5 1.	8
V _{CCPGM}	Configuration pins power supply	-0.5	3.75	V
V _{CCAUX}	Auxiliary supply for the programmable power technology	-0.	5 3.	75
V _{CCBAT}	Battery back-up power supply for design security volatile key re	gister -	0.5	3.75
V _{CCPD}	I/O pre-driver power supply	-0.5	3.75	V
V _{CCIO}	I/O power supply	-0.5	3.9	V
V _{CC_CLKIN}	Differential clock input power supply	-0.5	3.75	\
V _{CCD_PLL}	PLL digital power supply	-0.5	1.35	V
V _{CCA_PLL}	PLL analog power supply	-0.5	3.75	V
V _I	DC input voltage	-0.5	4.0	V
I _{OUT}	DC output current per pin	-25	40	m/
TJ	Operating junction temperature	-55	125	°(
T _{STG}	Storage temperature (No bias)	-65	150	°(

Table 1–2. Transceiver Power Supply Absolute Maximum Ratings for Stratix IV GX Devices

Symbol	Description	Minimum	Maximum	Unit
V _{CCA_L}	Transceiver high voltage power (left side)	-0.5	3.75	,
V_{CCA_R}	Transceiver high voltage power (right side)	-0.5	3.75	,
V _{CCHIP_L}	Transceiver HIP digital power (left side)	-0.5	1.35	,
V _{CCHIP_R}	Transceiver HIP digital power (right side)	-0.5	1.35	,
V _{CCR_L}	Receiver power (left side)	-0.5	1.35	V
V _{CCR_R}	Receiver power (right side)	-0.5	1.35	V
V _{CCT_L}	Transmitter power (left side)	-0.5	1.35	V
V _{CCT_R}	Transmitter power (right side)	-0.5	1.35	V
V _{CCL_GXBL} (1)	Transceiver clock power (left side)	-0.5	1.35	\
V _{CCL_GXBRn} ⁽¹⁾	Transceiver clock power (right side)	-0.5	1.35	\
V _{CCH_GXBL} n ⁽¹⁾	Transmitter output buffer power (left side)	-0.5	1.8	\
V _{CCH_GXBR} n ⁽¹⁾	Transmitter output buffer power (right side)	-0.5	1.8	\

Note to Table 1-2:

(1) n = 0, 1, 2, or 3.

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage shown in Table 1–4 and undershoot to -2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

Table 1–4lists the maximum allowed input oversh oot voltage and the duration of the overshoot voltage as a percentage ofdevice lifetime. The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% duty cycle. For example, a signal that overshoots to 4.3 V can only be at 4.3 V for~5% over the lifetime of the device; for a device lifetime of 10 years, this amounts to half of a year.

Table 1-4. Maximum Allowed Overshoot During Transitions

Symbol	Description	Condition (V)	Overshoot Duration as % of High Time	Unit
		4.0	100.000	%
		4.05	79.330	%
		4.1	46.270	%
		4.15	27.030	%
		4.2	15.800	%
		4.25	9.240	%
Vi (AC)	AC input voltage	4.3	5.410	%
		4.35	3.160	%
		4.4	1.850	%
		4.45	1.080	%
		4.5	0.630	%
		4.55	0.370	%
		4.6	0.220	%

Temperature Overshoot Above Maximum Allowed Temperature

The maximum allowed operating temperature for Stratix IV industrial grade devices is 100 °C. It is recommended that the operating temperature of the device is maintained below 100 °C at all times. The temperature excursions over 100 °C due to internal heating of the device should not exceed the number of cycles as specified in the Table 1–5 Exceeding the recommended number of cycles may cause solder interconnect failures. Altera [®] recommends using the Stratix IV military grade devices if the application requires operating temperatures over 100 °C.

Table 1-5. Temperature Overshoot Above Maximum Allowed Temperature

Description	Operating Temperature (°C)	Number of Cycles Over 100 °C
	100	3200
	105	768
Device operating	110	640
temperature (°C)	115	480
	120	320
	125	160

Table 1–11. OCT Calibration Accuracy Specifications for Stratix IV Devices (Part 2 of 2) (1)

Symbol	Doggrintion	Conditions	Calib	oration Accui	acy	Unit
Symbol	Description	Conunctions	C2	C3,I3, M3	C4,I4	UIIIL
25-Ω R _{S_left_shift} 3.0, 2.5, 1.8, 1.5, 1.2	Internal left shift series termination with calibration (25-Ω R _{S_left_shif} setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	± 10	± 10	± 10	%

Notes to Table 1-11:

- (1) OCT calibration accurasyalid at the timef calibration only.
- (2) 25Ω R_S is not supported for 1.5 V and 1.2 V in Row I/O.
- (3) 20Ω R_S is not supported for 1.5 V and 1.2 V in Row I/O.

The calibration accuracy for calibrated series and parallel OCTs are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change. Table 1–12 lists the Stratix IV OCT without calibration resistance tolerance to PVT changes.

Table 1–12. OCT Without Calibration Resistance Tolerance Specifications for Stratix IV Devices

Ob-d	Paradali ar	0.004141.000	Resi	stance Tolera	ance	
Symbol	Description	Conditions	C2	C3,I3, M3	C4,I4	Unit
25-Ω R _S 3.0 and 2.5	Internal series termination without calibration (25 setting)	V _{CCIO} = 3.0 and 2.5 V	' ± 30	± 40	± 40	9/6
25-Ω R _S 1.8 and 1.5	Internal series termination without calibration (25 setting)	V _{CCIO} = 1.8 and 1.5 \	± 30	± 40	± 40	*/
25-Ω R _S 1.2	Internal series termination without calibration (25 setting)	V _{CCIO} = 1.2 V	± 35	± 50	± 50	%
50-Ω R _S 3.0 and 2.5	Internal series termination without calibration (50 setting)	V _{CCIO} = 3.0 and 2.5 V	' ± 30	± 40	± 40	9/6
50-Ω R _S 1.8 and 1.5	Internal series termination without calibration (50 setting)	V _{CCIO} = 1.8 and 1.5 V	' ± 30	± 40	± 40	9/6
50-Ω R _S 1.2	Internal series termination without calibration (50 setting)	V _{CCIO} = 1.2 V	± 35	± 50	± 50	%
100Ω R _D 2.5	Internal differential termination (1002 setting)	V _{CCIO} = 2.5 V	± 25	± 25	± 25	%

Table 1–14. Pin Capacitance for Stratix IV Devices (Part 2 of 2)

Symbol	Description	Value	Unit	
C _{OUTFB}	Input capacitance on the dual-purpose clock output and feedback	pins	5	pF
C _{CLK1} C _{CLK3} C _{CLK8} and G _{LK10}	Input capacitance for dedicated clock input pins	2	ı	ρ F

Hot Socketing

Table 1–15lists the hot socketing specifications for Stratix IV devices.

Table 1–15. Hot Socketing Specifications for Stratix IV Devices

Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300
I _{IOPIN (AC)}	AC current per I/O pin	8 m/A
I _{XCVR-TX (DC)}	DC current per transceiver TX pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver RX pin	50 mA

Note to Table 1-15:

Internal Weak Pull-Up Resistor

Table 1–16lists the weak pull-up resistor values for Stratix IV devices.

Table 1–16. Internal Weak Pull-Up Resistor for Stratix IV Devices (1), (3)

Symbol	Description	Conditions (V)	Value ⁽⁴⁾	Unit
		$V_{CCIO} = 3.0 \pm 5\%^{(2)}$	25	kΩ
	Value of the I/O pin pull-up resistor before	V _{CCIO} = 2.5 ±5% ⁽²⁾	25	kΩ
R_{PU}	and during configuration, as well as user mode if the programmable pull-up resistor	r V _{CCIO} = 1.8 ±5% ⁽²⁾	25	kΩ
	option is enabled.	V _{CCIO} = 1.5 ±5% ⁽²⁾	25	kΩ
		V _{CCIO} = 1.2 ±5% ⁽²⁾	25	kΩ

Notes to Table 1-16:

- (1) All I/O pins have an option to enable weakupuexcept configuration, test, and JTAG pins.
- (2) Pin pull-up resistance values be lower if an external sc drives the pin higher that the column of the colum
- (3) The internal weak pull-down feature is only available for the CNTAG. The typical value for this eimal weak pull-down resistor is approximately 25Ω .
- (4) These specifications are valid with ±10Perances to cover changes over PVT.

⁽¹⁾ The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 kg/s= 10 dv/dt, in which C is the I/O pin capacitance and dv/dt is the slew rate.

Transceiver Performance Specifications

This section describes transceiver performance specifications.

Table 1–23lists the Stratix IV GX transceiver specifications.

Table 1–23. Transceiver Specifications for Stratix IV GX Devices (Part 1 of 9)

Symbol/ Description	Conditions		Commer eed Gra		Ind -2×	Commerc lustrial a Commer eed Grade	nd cial	Comm	Military and –4 ercial/Ind peed Gra	dustrial	Unit
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Reference Clock											
Supported I/O Standards	1.2 V PCI	ML, 1.4	V PCM	/IL 1.5 \	/ PCMI	_, 2.5 V I	PCML,	Differen	tial ĽV,R	ØO S, HO	CSL
Input frequency from REFCLK input pins	_	50	_	697	50	_	697	50		637.5	МН
Phase frequency detector (CMU PLL and receiver CDR)	_	50	_	425	50	_	325	50		325	MH
Absolute M _{AX} for a REFCLK pin	_	_	_	1.6	_	_	1.6	_		1.6	V
Operational Maxfor a REFCLK pin	_	_	_	1.5	_	_	1.5	_		1.5	V
Absolute M _{IN} for a REFCLK pin	_	-0.4	_	_	-0.4	_	_	-0.4	_	_	V
Rise/fall time ⁽²¹⁾	_	_	_	0.2	_	_	0.2	_	_	0.2	UI
Duty cycle	_	45	_	55	45	_	55	45	_	55	%
Peak-to-peak differential input voltage	_	200		1600	200		1600) 200		160) m\
Spread-spectrum modulating clock frequency	PCle	30		33	30		33	30		33	kH
Spread-spectrum downspread	PCle	_	0 to -0.5%	_	_	0 to -0.5%	_	_	0 to -0.5%	_	_
On-chip termination resistors	_	_	100	_	_	100	_	_	100	_	Ω
V _{ICM} (AC coupled)			1100 ±	10%		1100 ±	10%		1100	± 10%	
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250		550	250	_	550	250	_	550	m∖

Table 1–23. Transceiver Specifications for Stratix IV GX Devices (Part 5 of 9)

Symbol/ Description	Conditions	–2 Commercial Speed Grade			–3 Commercial/ Industrial and –2× Commercial Speed Grade ⁽¹⁾			–3 Commo S _l	Unit		
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	DC Gain Settin = 0	g	0	_	_	0	_	_	0	_	dB
	DC Gain Settin = 1	g	3	_	1	3	_	_	3	_	dB
Programmable DC gain	DC Gain Settin = 2	g	6	_		6	_	_	6	_	dB
	DC Gain Settin = 3	g	9	_	_	9	_	_	9	_	dB
	DC Gain Settin = 4	g	12	_	_	12	_		12	_	dB
EyeQ Data Rate	_	60	0 –	32	50 60	00 –	- 32	250 6	00	— 3	250 M
AEQ Data Rate	min V _D (diff p-p) outer envelope = 600 mV 8B/10B encoded data	2500	_	6500	2500	_	6500) —	_	_	Mbps
Decision Feedback Equalizer (DFE) Da Rate	min V _D (diff p-p) ta outer envelope = 500 mV	3125		6500	3125	_	6500) —		_	Mbps
Transmitter											
Supported I/O Standards				1.4	4 V PCI	ИL, 1.5 \	/ PCML	-			
Data rate (Single width, non-PMA Direct)	1	600		3750	600	_	3750	600		3750	Mbps
Data rate (Double width, non-PMA Direct)	_	1000	_	8500	1000	_	6500	1000) —	6375 (22)	Mbps
Data rate (Single width, PMA Direct)	_	600	_	3250	600	_	3250	600	_	3250) Mbps
Data rate (Double width, PMA Direct)	_	1000	_	6500	1000	_	6500	1000) —	637	5 Mbp
V _{OCM}	0.65 V setting		650	_		650			650		mV
	85–Ω setting		85 ± 15	5%		85 ± 15	5%		85 ±	15%	Ω
Differential on-chip termination	100– Ω setting	,	100 ± 1	5%		100 ± 1	5%		100 ±	: 15%	Ω
resistors	120-Ω setting	,	120 ± 1	5%		120 ± 1	5%		120 ±	: 15%	Ω
	150 Ω setting	•	150 ± 1	5%		150 ± 1	5%		150 ±	: 15%	Ω

Table 1–23. Transceiver Specifications for Stratix IV GX Devices (Part 7 of 9)

Symbol/ Description	Conditions		Commer eed Gra		Ind −2×	Commerc Iustrial a Commer ed Grade	nd cial	Commo	Military and –4 ercial/Ind peed Gra	dustrial	Unit
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Inter-transceiver block skew in Basic	N < 18 channels located across three transceiver blocks with the source CMU PLL located in the center transceiver block		1	400		_	400		l	400	ps
(PMA Direct) ×N mode ⁽¹⁵⁾	Daoid		l	650		_	650		ļ	650	ps
CMUO PLL and CMU1	PLL										
Supported Data Range	_	600	_	8500	600	_	6500	600	_	637	5 Mbp
pll_powerdown minimum pulse width (tpll_powerdown)	_					1					μS
CMU PLL lock time from pll_powerdown de-assertion	-		_	100		_	100	_	_	100	μS

Table 1–25through Table 1–28lists the typical differential V $_{
m OD}$ termination settings for Stratix IV GX and GT devices.

Table 1–25. Typical V $_{\text{OD}}$ Setting, TX Term = 85 Ω

Sumbol	V _{OD} Setting (mV)										
Symbol	0	1	2	3	4	5	6	7			
V _{OD} differential	170 ±	340 ±	510 ±	595 ±	680 ±	765 ±	850 ±	1020±			
peak-to-peak Typical (m	V)20%	20%	20%	20%	20%	20%	20%	20%			

Table 1–26. Typical V_{0D} Setting, TX Term = 100 Ω

Sumbol	V _{OD} Setting (mV)									
Symbol	0	1	2	3	4	5	6	7		
V _{OD} differential peak-to-peak Typical (m	200 ± V)20%	400 ± 20%	600 ± 20%	700 ± 20%	800 ± 20%	900 ± 20%	1000 ± 20%	1200 ± 20%		

Table 1–27. Typical V_{0D} Setting, TX Term = 120 Ω

V _{OD} Setting (mV)									
0	1	2	3	4	5	6			
240 ±	480 ±	720 ±	840 ±	960 ±	1080 ±	1200 ± 20%			
	0 240 ± /) 20%		0 1 2 240 ± 480 ± 720 ±	0 1 2 3 240 ± 480 ± 720 ± 840 ±	0 1 2 3 4 240 ± 480 ± 720 ± 840 ± 960 ±	0 1 2 3 4 5 240 ± 480 ± 720 ± 840 ± 960 ± 1080 ±			

Table 1–28. Typical V_{0D} Setting, TX Term = 150 Ω

Symbol		V _{OD} Setting (mV)									
Symbol	0	1	2	3	4	5					
V _{OD} differential peak-to-peak Typical (m)	300 ± V) 20%	600 ± 20%	900 ± 20%	1050 ± 20%	1200 ± 20%	1350 ± 20%					

Table 1–29lists typical transmitter pre-emphasis levels in dB for the first post tap under the following conditions (low-frequency data pattern [five 1s and five 0s] at 6.25 Gbps). The levels listed inTable 1–29are a representation of possible pre-emphasis levels under the specified conditions only and that the pre-emphasis levels may change with data pattern and data rate.

To predict the pre-emphasis level for your specific data rate and pattern, run simulations using the Stratix IV HSSI HSPICE models.

Table 1-29. Transmitter Pre-Emphasis Levels for Stratix IV Devices (Part 1 of 2)

Pre-Emphasis 1st		V _{OD} Setting										
Pre-Emphasis 1st Post-Tap Setting	0	1	2	3	4	5	6	7				
0	0	0	0	0	0	0	0	0				
1	N/A	0.7	0	0	0	0	0	0				
2	N/A	1	0.3	0	0	0	0	0				
3	N/A	1.5	0.6	0	0	0	0	0				

Table 1–29. Transmitter Pre-Emphasis Levels for Stratix IV Devices (Part 2 of 2)

Pre-Emphasis 1st		V _{OD} Setting											
Post-Tap Setting	0	1	2	3	4	5	6	7					
4	N/A	2	0.7	0.3	0	0	0	0					
5	N/A	2.7	1.2	0.5	0.3	0	0	0					
6	N/A	3.1	1.3	0.8	0.5	0.2	0	0					
7	N/A	3.7	1.8	1.1	0.7	0.4	0.2	0					
8	N/A	4.2	2.1	1.3	0.9	0.6	0.3	0					
9	N/A	4.9	2.4	1.6	1.2	0.8	0.5	0.2					
10	N/A	5.4	2.8	1.9	1.4	1	0.7	0.3					
11	N/A	6	3.2	2.2	1.7	1.2	0.9	0.4					
12	N/A	6.8	3.5	2.6	1.9	1.4	1.1	0.6					
13	N/A	7.5	3.8	2.8	2.1	1.6	1.2	0.6					
14	N/A	8.1	4.2	3.1	2.3	1.7	1.3	0.7					
15	N/A	8.8	4.5	3.4	2.6	1.9	1.5	0.8					
16	N/A	N/A	4.9	3.7	2.9	2.2	1.7	0.9					
17	N/A	N/A	5.3	4	3.1	2.4	1.8	1.1					
18	N/A	N/A	5.7	4.4	3.4	2.6	2	1.2					
19	N/A	N/A	6.1	4.7	3.6	2.8	2.2	1.4					
20	N/A	N/A	6.6	5.1	4	3.1	2.4	1.5					
21	N/A	N/A	7	5.4	4.3	3.3	2.7	1.7					
22	N/A	N/A	8	6.1	4.8	3.8	3	2					
23	N/A	N/A	9	6.8	5.4	4.3	3.4	2.3					
24	N/A	N/A	10	7.6	6	4.8	3.9	2.6					
25	N/A	N/A	11.4	8.4	6.8	5.4	4.4	3					
26	N/A	N/A	12.6	9.4	7.4	5.9	4.9	3.3					
27	N/A	N/A	N/A	10.3	8.1	6.4	5.3	3.6					
28	N/A	N/A	N/A	11.3	8.8	7.1	5.8	4					
29	N/A	N/A	N/A	12.5	9.6	7.7	6.3	4.3					
30	N/A	N/A	N/A	N/A	11.4	9	7.4	N/A					
31	N/A	N/A	N/A	N/A	12.9	10	8.2	N/A					

Table 1–30. Transceiver Block Jitter Specifications for Stratix IV GX Devices (1), (2) (Part 3 of 9)

Min Typ Max Min Typ Max Min Typ Max Min Typ Max Min Total jitter at 5 Gbps (Gen2) Compliance pattern Compliant Compliant Compliant Compliant Compliant Compliant Compliant Compliant	Typ Max — 5 — 17	75	
(Gen2) Compliance pattern Compliant Compliant PCIe (Gen 1) Electrical Idle Detect Threshold V _{RX-IDLE-DETDIFFp} . Compliance pattern 65 + 175 65 + 175 65	5 – 1	75	
V _{RX-IDLE-DETDIFFp-P} Compliance pattern 65 + 175 65 + 175 65	5 — 1	7 5	
	5 — 1	75	
Serial RapidIO Transmit Jitter Generation (8)		_	
Deterministic jitter (peak-to-peak) Data Rate = 1.25, 2.5,	_ 0.17	UI	
Pattern = CJPA1			
Total jitter (peak-to-peak) Data Rate = 1.25, 2.5, 3.125 Gbps — — 0.35 — — 0.35 — 0.35 — 0.35 — — 0.35 — — 0.35 — 0.3	- 0.35	UI	
Serial RapidIO Receiver Jitter Tolerance (8)			
Deterministic jitter tolerance (peak-to-peak) Pattern = CJPAT Data Rate = 1.25, 2.5, 3.125 Gbps > 0.37 > 0.37	> 0.37		
Combined deterministic Data Rate = 1.25, 2.5, and random jitter 3.125 Gbps > 0.55 > 0.55 tolerance (peak-to-peak) attern = CJPAT	> 0.55	U	
Jitter Frequency = 22.1 KHz Data Rate = 1.25, 2.5, 3.125 Gbps > 8.5 > 8.5	> 8.5	UI	
Pattern = CJPAT Jitter Frequency = 1.875			
MHz Sinusoidal jitter Data Rate = 1.25, 2.5, tolerance (peak-to-peak) 2.125 Gbps	> 0.1		
Pattern = CJPAT			
Jitter Frequency = 20 MHz			
Data Rate = 1.25, 2.5, > 0.1 > 0.1 > 0.1	> 0.1	UI	
Pattern = CJPAT			
GIGE Transmit Jitter Generation ⁽⁹⁾			
Deterministic jitter (peak-to-peak) Pattern = CRPAT - 0.14 - 0.14 - 0.14	0.	14	
Total jitter (peak-to-peak) Pattern = CRPAT - 0.279 - 0.279 - 0.279	0.2	79	

Table 1-30. Tra	ınsceiver Block Jitter S	pecifications for Stratix	: IV GX Devices ⁽¹⁾ , ⁽²⁾	(Part 9 of 9)
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Symbol/ Description	Conditions	–2 Commercial Speed Grade			−3 Commercial/ Industrial and −2× Commercial Speed Grade			–3 N –4 (Indu	Unit		
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
	Jitter Frequency = 21.8 KHz	> 8.5		5	> 8.5			> 8.5			UI
Sinusoidal Jitter	Pattern = CJPAT										
tolerance at 3072 Mbps	Jitter Frequency = 1843.2 MHz to 20 MHz	> 0.1		1	> 0.1			> 0.1			UI
	Pattern = CJPAT										

Notes to Table 1-30:

- (1) Dedicated refclk pins were used to drue the input reference clocks.
- (2) The Jitter numbers are valid floe stated conditions only.
- (3) Stratix IV GX devices in militarpeed grade only support setabtransceiver configuration top3125 Mbps. For more infortion, contact Altera sales representative.
- (4) The jitter numbers for SONET/SDH are count plot the GR-253-CORE Issue 3 Specification.
- (5) The jitter numbers for Fibreachel are compliant the FC-PI-4 Specification revision 6.10.
- (6) The jitter numbers for XAUI are complito the IEEE802.3ae-2002 Specification.
- (7) The jitter numbers for PCI Express (PIPE) (ROCHE) ompliant to the RCB ase Specification 2.0.
- (8) The jitter numbers for Serial RapidlOcarepliant to the RapliO Specification 1.3.
- (9) The jitter numbers for GIGE are commobile the IEEE802.3-2002 Specification.
- (10) The jitter numbers for HiGig are coamplto the IEEE802.3ae-2002 Specification.
- (11) The jitter numbers for (OIF) CEI areptiant to the OIF-GE2.0 Specification.
- (12) The HD-SDI and 3G-SDI jitter numbers are contribit the SMPTE292M and SMPTE424M Specifications.
- (13) The fibre channel transmitjiturer generation numbers arenupliant to the specification at interoperability point.
- (14) The fibre channel receive teri tolerance numbers are comptito the specification at interoperability point.
- (15) You must use the ATX PLL adjacethtedransceiver channels/retuent the transmitter jitten eneration compliance in PCGen2 x8 modes.
- (16) Stratix IV PCIe receivers are communitor this specificion provided the tw.-CM-DC-ACTIVEIDLE-DEQFA the upstream transitter is less than 50mV.
- (17) The jitter numbers if Serial Attached SCSI (SAS) arrepolizant to the SA2.1 Specification.
- (18) The jitter numbers for CPRI are climant to the CPRI Specification V3.0.
- (19) The jitter numbefor OBSAI are compliant toetoBSAI RP3 Specification V4.1.

PLL Specifications

Table 1–34lists the Stratix IV PLL specifications when operating in the commercial (0° to 85°C), industrial (–40° to 100°C), and military (–55°C to 125°C) junction temperature ranges.

Table 1-34. PLL Specifications for Stratix IV Devices (Part 1 of 2)

Symbol	Parameter	Min	Тур	Max	Unit
	Input clock frequency (-2/-2x speed grade)		5 -	- (800	MHz
f _{IN}	Input clock frequency (–3 speed grade)		5 -	∀ 17	MHz
	Input clock frequency (–4 speed grade)		5 -	∀ 17	MHz
f _{INPFD}	Input frequency to the PFD	5	<u> </u>	325	MHz
	PLL VCO operating range (–2 speed grade)		600	— 16	00 M
f _{VCO} ⁽²⁾	PLL VCO operating range (–3 speed grade)		600	— 13	00 M
	PLL VCO operating range (–4 speed grade)		600	— 13	00 M
t _{EINDUTY}	Input clock or external feedback clock input duty cycle		40	— 6	0 9
	Output frequency for internal global or regional clock (–2/–2x speed grade)	_	_	800 (3)	MHz
f _{OUT}	Output frequency for internal global or regional clock (–3 speed grade)	_	_	717 ⁽³⁾	MHz
	Output frequency for internal global or regional clock (–4 speed grade)		_	717 ⁽³⁾	MHz
	Output frequency for external clock output (-2 speed g	rade)	_	— ⁽³⁾ 80	0 MHz
f _{OUT_EXT}	Output frequency for external clock output (-3 speed g	rade)		— ⁽³⁾ 71	7 MHz
	Output frequency for external clock output (-4 speed g	rade)	_	— ⁽³⁾ 71	7 MHz
t _{OUTDUTY}	Duty cycle for external clock output (when set to 50%)		45	50 5	55 9
t _{FCOMP}	External feedback clock compensation time			1() ns
t _{CONFIGPLL}	Time required to reconfigure scan chain	-	_ 3	.5 —	scanclk cycles
t _{CONFIGPHASE}	Time required to reconfigure phase shift	-		_	scanclk cycles
f _{SCANCLK}	scanclk frequency		_	100	MHz
t _{LOCK}	Time required to lock from end-of-device configuration de-assertion of areset	or_	_	1	ms
t _{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)		_	1	ms
	PLL closed-loop low bandwidth	_	0.3	3 —	MHz
f_{CLBW}	PLL closed-loop medium bandwidth	_	1.	5 —	MHz
	PLL closed-loop high bandwidth	_	4	_	MHz
t _{PLL_PSERR}	Accuracy of PLL phase shift	_	-	±50	ps
t _{ARESET}	Minimum pulse width on thereset signal	10	_	_	ns
+ (4) (5)	Input clock cycle to cycle jitter(F≥ 100 MHz)	_	_	0.15	UI (p-p)
t _{INCCJ} (4), (5)	Input clock cycle to cycle jitter (F< 100 MHz)	_	_	±750	ps (p-p)
. (6)	Period Jitter for dedicated clock output (€ 100 MHz)	_	_	175	ps (p-p)
t _{OUTPJ_DC} ⁽⁶⁾	Period Jitter for dedicated clock output (100 MHz)	_	_	17.5	mUI (p-p

Table 1-34. PLL Specifications for Stratix IV Devices (Part 2 of 2)

Symbol	Parameter	Min	Тур	Max	Unit
+ (6)	Cycle to Cycle Jitter for dedicated clock output $(F_{OUT} \ge 100 \text{ MHz})$	_	_	175	ps (p-p)
t _{OUTCCJ_D} c ⁶⁾	Cycle to Cycle Jitter for dedicated clock output (F _{OUT} < 100 MHz)	_	_	17.5	mUI (p-p)
t _{OUTPJ_IO} ⁽⁶⁾ ,	Period Jitter for clock output on regular I/O (F _{OUT} ≥ 100 MHz)	_	_	600	ps (p-p)
(9)	Period Jitter for clock output on regular I/O (F _{OUT} < 100 MHz)	_	_	60	mUI (p-p)
t _{OUTCCJ_IO} (6),	Cycle to Cycle Jitter for clock output on regular I/O $(F_{OUT} \ge 100 \text{ MHz})$	_	_	600	ps (p-p)
(9)	Cycle to Cycle Jitter for clock output on regular I/O (F _{OUT} < 100 MHz)	_	_	60	mUI (p-p)
t _{CASC_OUTPJ_DC}	Period Jitter for dedicated clock output in cascaded Pl $_2$ ($F_{OUT} \ge 100 MHz$)	Ls_	_	250	ps (p-p)
(6), (7)	Period Jitter for dedicated clock output in cascaded PL $(F_{OUT} < 100 MHz)$	Ls_	_	25	mUI (p-p)
f _{DRIFT}	Frequency drift after PFDENA is disabled for duration 100 us	of	_	±10	%

Notes to Table 1-34:

- (1) This specification is limited in theatQus II software by the I/Oaximum frequency. The maximut/O frequency is differtefor each I/O standard.
- (2) The VCO frequency reported by the to subtroof tware in the PLL summary section frequency report takes into considion the VCO post-scale counter K value. Therefore, if the counter K hause 201/20, the frequency repost can be lower than the specification.
- (3) This specification is limited the lower of the two: I/Q_{MX} or F_{OUT} of the PLL.
- (4) A high input jitter directly affectsetPLL output jitter. To have low PLL outptock jitter, you must provide a clearck source that is less than 120 ps.
- (5) F_{REF} is fIN/N when N = 1.
- (6) Peak-to-peak jitter withprobability level of 10 (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLwhen an input jitter of 30s is applied. The external memory interface clock output jitterifications use a different measurement rhed and are available Table 1–51 on page 1–62
- (7) The cascaded PLL specification is ${\bf epp}$ licable with the llowing condition:
 - A. Upstream PLL: 0.59MtszUpstream PLL BW < 1 MHz
 - B. Downstream PLL: Downstream PLL BW > 2 MHz
- (8) High bandwidth PLL settings are sumported in external feedback mode.
- (9) External memory interface clock out interface specifications use a different ansurement method, which is available 1-49 on page 1-61